

Title (en)
POLISHING PAD AND METHOD FOR MANUFACTURING SAME

Title (de)
POLIERKISSEN UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)
TAMPON À POLIR ET SON PROCÉDÉ DE FABRICATION

Publication
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Application
EP 13793745 A 20130212

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Abstract (en)
Polishing pad and method of manufacturing the same, the method, whereby materials for forming a polishing layer are mixed and solidified by a chemical reaction so as to manufacture the polishing pad, the method including: grinding organic materials by using a physical method so as to form micro-organic particles; mixing the micro-organic particles formed in the operation with the materials for forming the polishing layer; mixing at least one selected from the group consisting of inert gas, a capsule type foaming agent, and a chemical foaming agent that are capable of controlling sizes of pores, with the mixture in the operation so as to form gaseous pores; performing gelling and hardening of the mixture generated in the operation so as to form a polishing layer; and processing the polishing layer so as to distribute open pores defined by opening gaseous pores on a surface of the polishing layer.

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